

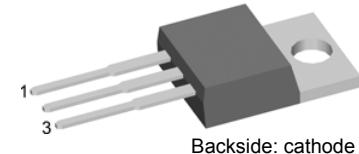
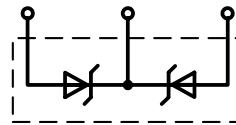
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**Schottky**

High Performance Schottky Diode  
 Low Loss and Soft Recovery  
 Common Cathode

Part number

DSA 30 C 60PB



Backside: cathode

**Features / Advantages:**

- Very low V<sub>f</sub>
- Extremely low switching losses
- Low I<sub>rm</sub>-values
- Improved thermal behaviour
- High reliability circuit operation
- Low voltage peaks for reduced protection circuits
- Low noise switching
- Low losses

**Applications:**

- Rectifiers in switch mode power supplies (SMPS)
- Free wheeling diode in low voltage converters

**Package:**

TO-220AB

- Industry standard outline
- Epoxy meets UL 94V-0
- RoHS compliant

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	Unit
V <sub>RRM</sub>	max. repetitive reverse voltage	T <sub>vJ</sub> = 25 °C			60	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = 60 V      T <sub>vJ</sub> = 25 °C V <sub>R</sub> = 60 V      T <sub>vJ</sub> = 125 °C		0.5 5	mA	mA
V <sub>F</sub>	forward voltage	I <sub>F</sub> = 15 A      T <sub>vJ</sub> = 25 °C I <sub>F</sub> = 30 A			0.85 0.95	V
		I <sub>F</sub> = 15 A      T <sub>vJ</sub> = 125 °C I <sub>F</sub> = 30 A			0.68 0.78	V
I <sub>FAV</sub>	average forward current	rectangular, d = 0.5      T <sub>c</sub> = 150 °C			15	A
V <sub>F0</sub> r <sub>F</sub>	threshold voltage slope resistance } for power loss calculation only				0.44 11.2	V mΩ
R <sub>thJC</sub>	thermal resistance junction to case				1.75	K/W
T <sub>vJ</sub>	virtual junction temperature		-55		175	°C
P <sub>tot</sub>	total power dissipation	T <sub>c</sub> = 25 °C			85	W
I <sub>FSM</sub>	max. forward surge current	t <sub>p</sub> = 10 ms (50 Hz), sine      T <sub>vJ</sub> = 45 °C			130	A
C <sub>J</sub>	junction capacitance	V <sub>R</sub> = tbd V; f = 1 MHz      T <sub>vJ</sub> = 25 °C		tbd		pF
E <sub>AS</sub>	non-repetitive avalanche energy	I <sub>AS</sub> = 1 A; L = 100 μH      T <sub>vJ</sub> = 25 °C			0.05	mJ
I <sub>AR</sub>	repetitive avalanche current	V <sub>A</sub> = 1.5 · V <sub>R</sub> typ.; f = 10 kHz			0.1	A

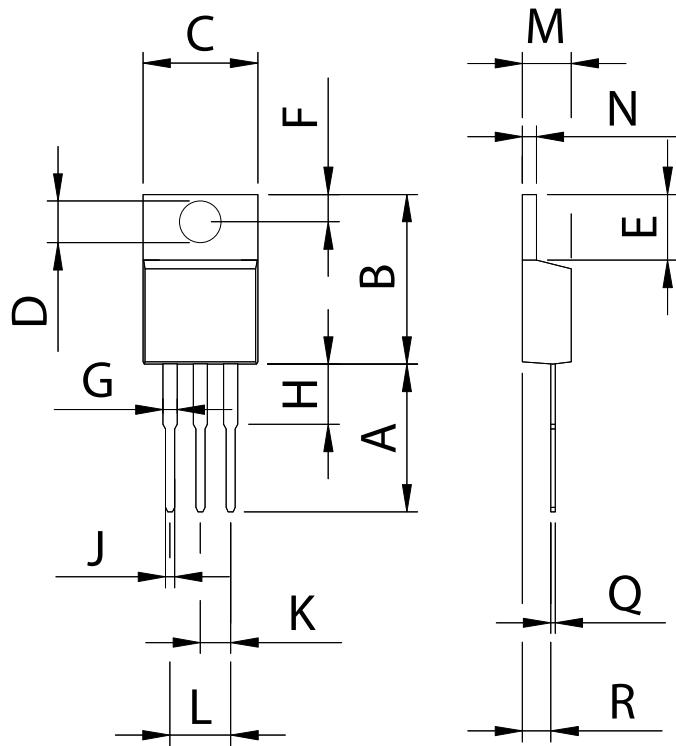
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Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
$I_{RMS}$	RMS current	per pin*			35	A
$R_{thCH}$	thermal resistance case to heatsink			0.50		K/W
$M_D$	mounting torque		0.4		0.6	Nm
$F_c$	mounting force with clip		20		60	N
$T_{stg}$	storage temperature		-55		150	°C
Weight				2		g

\*  $I_{RMS}$  is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

### Outlines TO-220AB



Dim.	Millimeter		Inches	
	Min.	Max.	Min.	Max.
A	12.70	13.97	0.500	0.550
B	14.73	16.00	0.580	0.630
C	9.91	10.66	0.390	0.420
D	3.54	4.08	0.139	0.161
E	5.85	6.85	0.230	0.270
F	2.54	3.18	0.100	0.125
G	1.15	1.65	0.045	0.065
H	2.79	5.84	0.110	0.230
J	0.64	1.01	0.025	0.040
K	2.54	BSC	0.100	BSC
M	4.32	4.82	0.170	0.190
N	1.14	1.39	0.045	0.055
Q	0.35	0.56	0.014	0.022
R	2.29	2.79	0.090	0.110